

# CMS23N06H8-HF

**N-Channel  
RoHS Device  
Halogen Free**



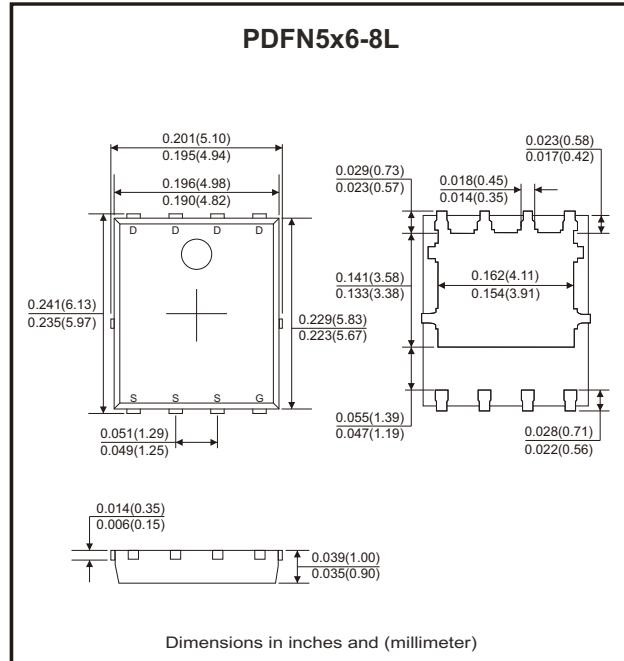
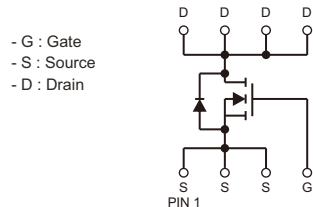
## Features

- Ultra-low on-resistance and gate-charge.
- Advanced shielded-gate technology.

## Mechanical data

- Case: PDFN5x6-8L, molded plastic.
- Molding compound: UL flammability classification rating 94V-0.
- Terminals: Matte tin-plated leads, solderability-per MIL-STD-202, method 208.

## Circuit Diagram



## Maximum Ratings

(at TA=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	V <sub>DSS</sub>	60	V
Gate-source voltage	V <sub>GSS</sub>	±20	V
Continuous drain current (Tc=25°C, silicon limited) (Note 1)	I <sub>D</sub>	125	A
Continuous drain current (Tc=100°C, silicon limited) (Note 1)	I <sub>D</sub>	79	
Continuous drain current (TA=25°C, silicon limited) (Note 2, 3)	I <sub>D</sub>	23	
Continuous drain current (TA=100°C, silicon limited) (Note 2, 3)	I <sub>D</sub>	14	
Pulsed drain current (tp=1ms) (Note 4)	I <sub>DM</sub>	370	A
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	110	mJ
Avalanche current (Note 6)	I <sub>AS</sub>	40	A
Power dissipation (Tc=25°C)	P <sub>D</sub>	86	W
Thermal resistance junction to case	R <sub>θJC</sub>	1.45	°C/W
Thermal resistance junction to air (Note 3)	R <sub>θJA</sub>	45	°C/W
Operating junction temperature range	T <sub>J</sub>	-55 to +150	°C
Storage temperature range	T <sub>STG</sub>	-55 to +150	°C

Notes: 1. Rated according to R<sub>θJC</sub>.

2. Rated according to R<sub>θJA</sub>.

3. Surface-mounted on 1 inch<sup>2</sup> FR4 board, 2oz Cu.

4. Limited by maximum T<sub>J</sub>.

5. Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>GS</sub>=10V, L=0.1mH.

6. Pulse width limited by maximum T<sub>J</sub>.

**Electrical Characteristics** (at  $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	60			V
Zero gate voltage drain current	$I_{DS(0)}$	$V_{DS} = 60V, V_{GS} = 0V$			1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
Static drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20\text{A}$		2.6	3.1	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 20\text{A}$		3.5	4.4	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.8	2.5	V
Forward transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 30\text{A}$		92		S
Gate resistance	$R_g$	$f = 1\text{MHz}$		1		$\Omega$
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$		3467		$\text{pF}$
Output capacitance	$C_{oss}$			1400		
Reverse transfer capacitance	$C_{rss}$			50		
Total gate charge	$Q_g$	$V_{DD} = 30V, V_{GS} = 10V, I_D = 30\text{A}$		64		$\text{nC}$
Gate to source charge	$Q_{gs}$			8		
Gate to drain (miller) charge	$Q_{gd}$			12		
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 30V, V_{GS} = 10V, R_G = 3\Omega, I_D = 15\text{A}$		23		$\text{ns}$
Turn-on rise time	$t_r$			62		
Turn-off delay time	$t_{d(off)}$			105		
Turn-off fall time	$t_f$			28		
<b>Source-Drain Diode Characteristics</b>						
Diode forward voltage	$V_{SD}$	$I_S = 30\text{A}, V_{GS} = 0V$		0.8		V
Reverse recovery time	$t_{rr}$	$I_S = 30\text{A}, V_{GS} = 0V, dI/dt = 100\text{A}/\mu\text{s}$ $T_b = 25\%$		55		$\text{ns}$
Reverse recovery charge	$Q_{rr}$			80		

## Rating and Characteristic Curves (CMS23N06H8-HF)

Fig.1 - Output Characteristics

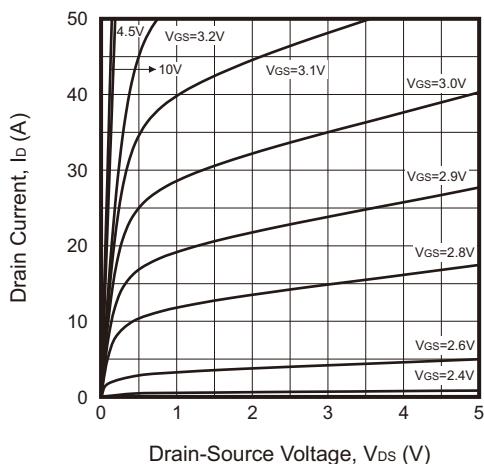


Fig.2 - On-Resistance vs. Drain Current

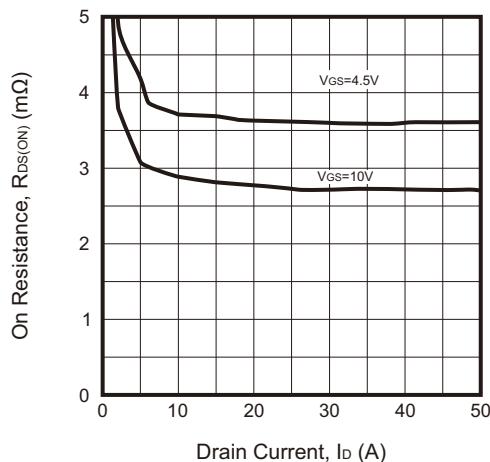


Fig.3 - On-Resistance vs. Gate-Source Voltage

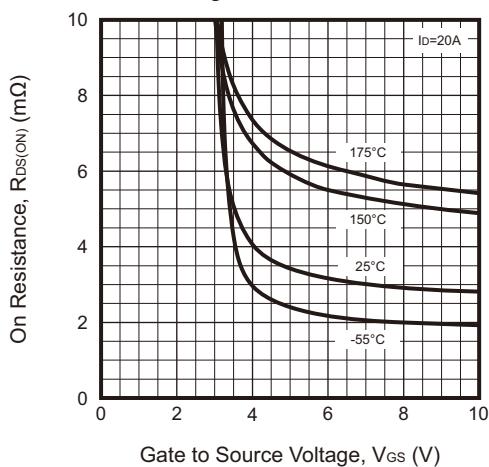


Fig.4 - Body-Diode Characteristics

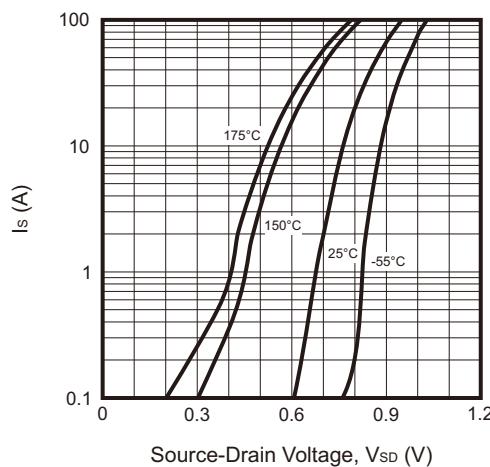


Fig.5 - Capacitance Characteristics

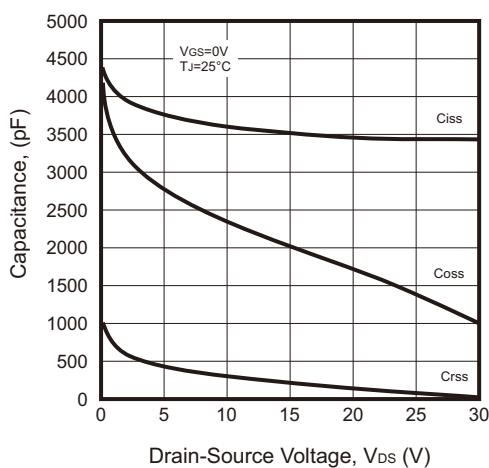
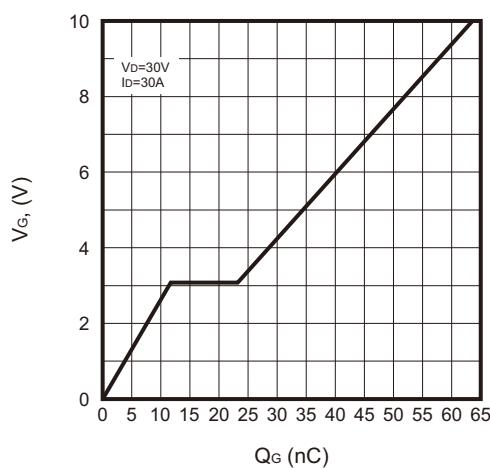


Fig.6 - Gate-Change Characteristics



## Rating and Characteristic Curves (CMS23N06H8-HF)

Fig.7 - Transfer Characteristics

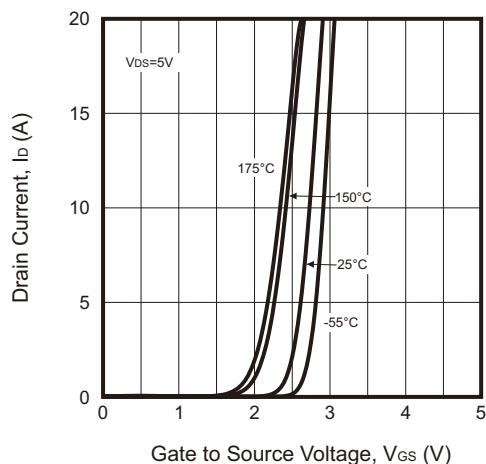


Fig.8 - Normalized  $R_{DS(ON)}$  vs  $T_J$

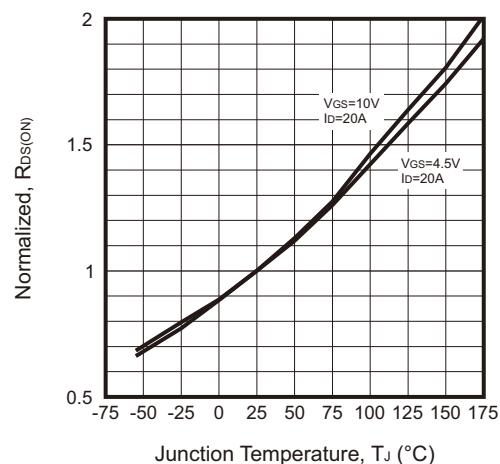


Fig.9 - Normalized  $V_{GS(th)}$  vs  $T_J$

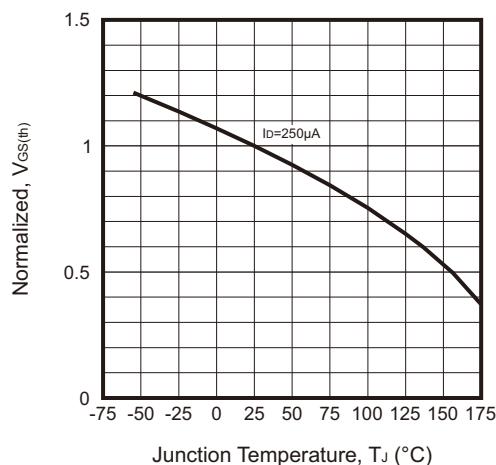


Fig.10 -  $BV_{DSS}$  vs  $T_J$

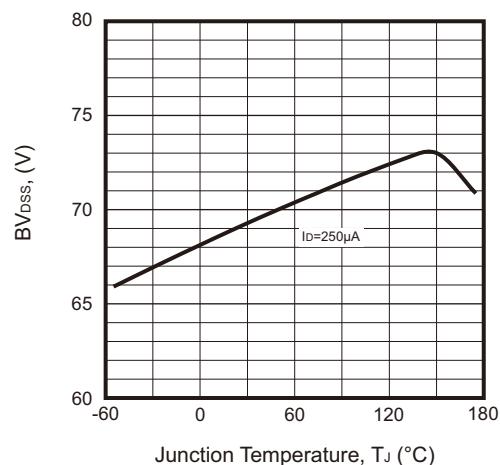
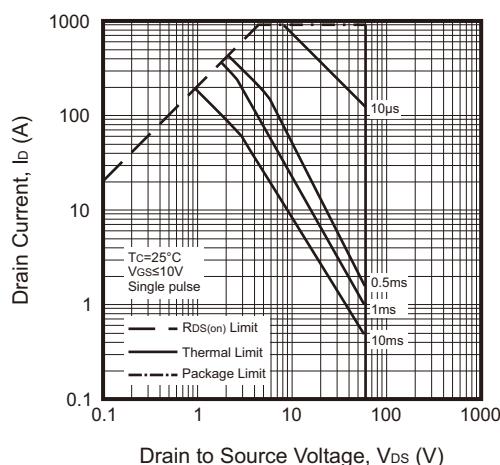
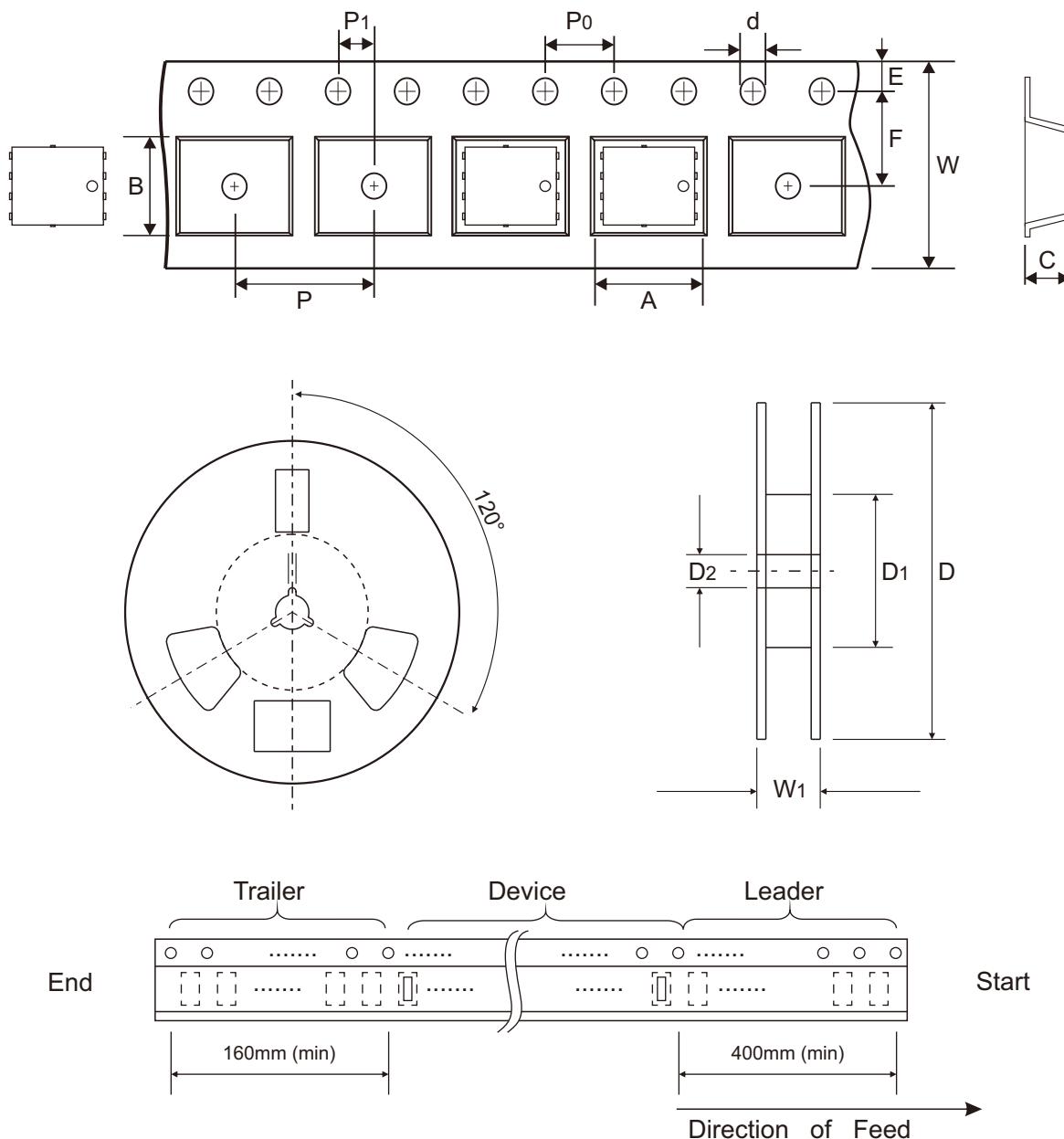


Fig.11 - Maximum Safe Operating Area



## Reel Taping Specification

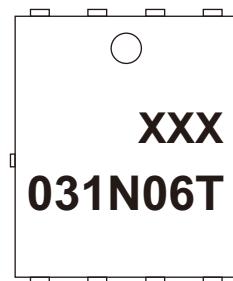


	SYMBOL	A	B	C	d	D	D1	D2
PDFN5x6 -8L	(mm)	6.30 ± 0.10	5.30 ± 0.10	1.20 ± 0.10	1.55 + 0.01	330 ± 1.00	100 ± 1.00	13.00 ± 0.20
	(inch)	0.248 ± 0.004	0.209 ± 0.004	0.047 ± 0.004	0.061 + 0.0004	12.992 ± 0.039	3.937 ± 0.039	0.512 ± 0.008

	SYMBOL	E	F	P	P0	P1	W	W1
PDFN5x6 -8L	(mm)	1.75 ± 0.10	5.50 ± 0.10	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	12.00 + 0.30 - 0.10	17.80 ± 0.30
	(inch)	0.069 ± 0.004	0.217 ± 0.004	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.472 + 0.012 - 0.004	0.701 ± 0.012

## Marking Code

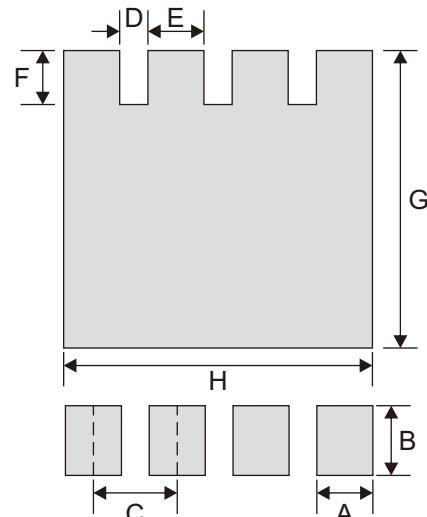
Part Number	Marking Code
CMS23N06H8-HF	031N06T



XXX = Control code

## Suggested P.C.B. PAD Layout

SIZE	PDFN5x6-8L	
	(mm)	(inch)
A	0.80	0.031
B	1.00	0.039
C	1.27	0.050
D	0.47	0.019
E	0.80	0.031
F	0.85	0.033
G	4.50	0.177
H	4.60	0.181



## Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
PDFN5x6-8L	5,000	13